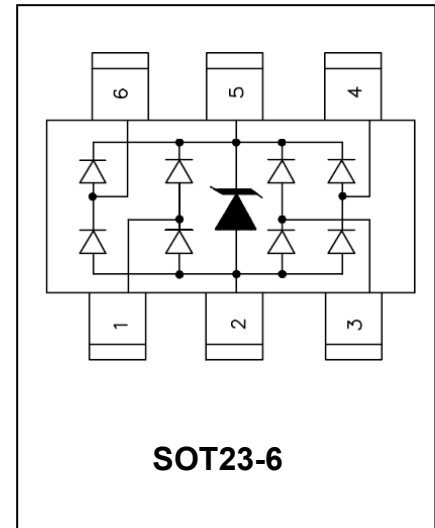


Features

- ◆ 250 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects four I/O lines
- ◆ Low capacitance ($< 1pF$) for high-speed interfaces
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

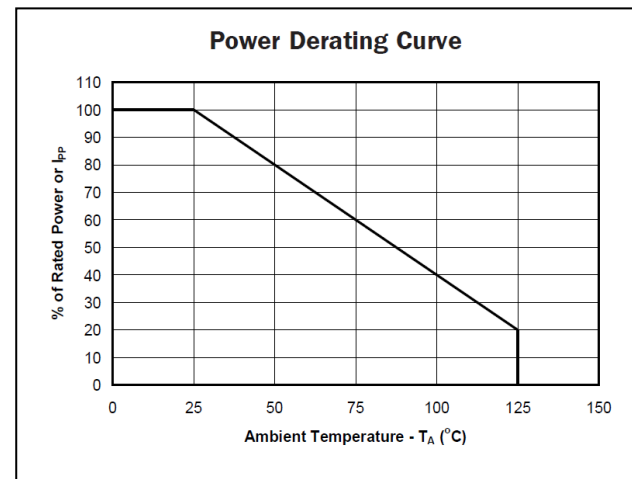
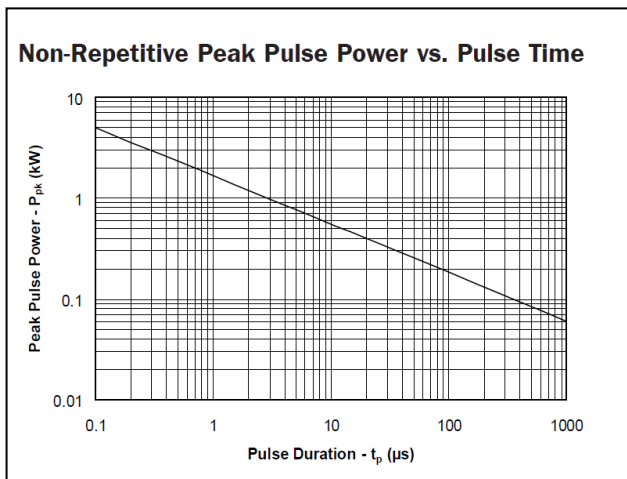
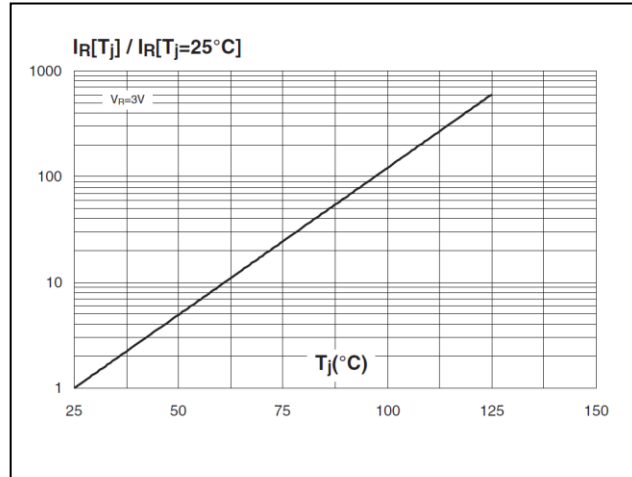
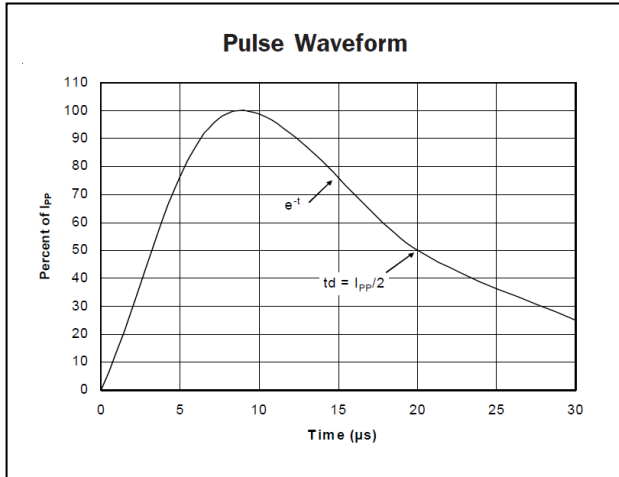
Maximum Rating @ $T_a = 25^\circ C$ unless otherwise specified

Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	250	Watts
T_L	Lead Soldering Temperature	260(10sec.)	$^\circ C$
T_J	Operating Temperature	-55 to +125	$^\circ C$
T_{STG}	Storage Temperature	-55 to +150	$^\circ C$

Electrical Characteristics@ Ta=25°C unless otherwise

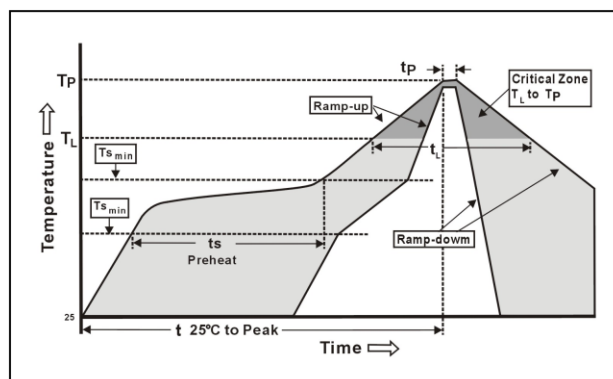
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{RWM}	Reverse Working Voltage	Any I/O to Ground			5.0	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1mA$, Any I/O to Ground	6.0			V
I_R	Reverse Leakage Current	$V_{RWM} = 5V$, Any I/O to Ground			1	μA
V_C	Clamping Voltage	$I_{PP} = 1A$, $t_p = 8/20\mu s$, any I/O pin to Ground			9.8	V
		$I_{PP} = 10A$, $t_p = 8/20\mu s$, any I/O pin to Ground			25	V
C_J	Junction Capacitance	$V_R = 0V$, $f = 1MHz$, between I/O pins		1	1.5	pF
		$V_R = 0V$, $f = 1MHz$, any I/O pin to Ground		1.5	3	pF

Typical Characteristics@ Ta=25°C unless otherwise specified



Soldering Parameters

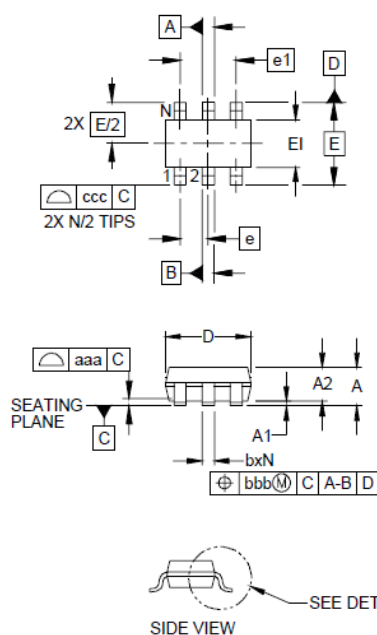
Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(\text{Min})}$)	150°C
	- Temperature Max ($T_{s(\text{Max})}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{s(\text{Max})}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



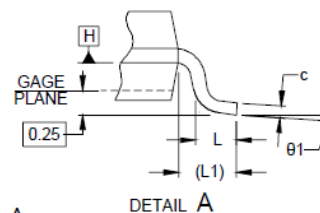
Package Outline

Plastic surface mounted package

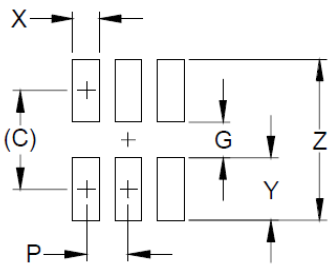
SOT23-6



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.035	-	.057	0.90	-	1.45
A1	.000	-	.006	0.00	-	0.15
A2	.035	.045	.051	.90	1.15	1.30
b	.010	-	.020	0.25	-	0.50
c	.003	-	.009	0.08	-	0.22
D	.110	.114	.122	2.80	2.90	3.10
E1	.060	.063	.069	1.50	1.60	1.75
E	.110 BSC			2.80 BSC		
e	.037 BSC			0.95 BSC		
e1	.075 BSC			1.90 BSC		
L	.012	.018	.024	0.30	0.45	0.60
L1		(.024)			(0.60)	
N	6			6		
θ_1	0°	-	10°	0°	-	10°
aaa	.004			0.10		
bbb	.008			0.20		
ccc	.008			0.20		



Soldering Footprint



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.098)	(2.50)
G	.055	1.40
P	.037	0.95
X	.024	0.60
Y	.043	1.10
Z	.141	3.60

Package And Marking Information

Device	Package	Shipping	Reel Size
SRV05-4R	SOT23-6	3000/Reel	7 inch